

TOPAZ
SEMICONDUCTOR

**SD1137, TN0106
TN0110**

**N-CHANNEL ENHANCEMENT-MODE
D-MOS POWER FETs**

T-29-25

ORDERING INFORMATION

TO-226AA (TO-92) Plastic Package	SD1137BD	TN0106N3	TN0110N3
Sorted Chips In Waffle Pack	SD1137CHP	TN0106ND	TN0110ND
Description	60V, 2.5 ohm	60V, 3.0 ohm	100V, 3.0 ohm

FEATURES

- Low Threshold,, $V_{GS(th)}$ 1.5V max
- Low Output and Transfer Capacitance
- Extended Safe Operating Area
- Complementary P-Channel Drivers Available

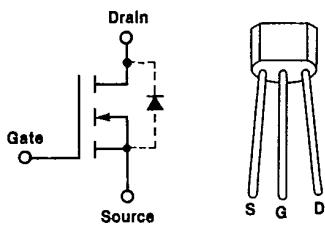
APPLICATIONS

- Complementary Voltage and Current Drivers
- Line Drivers
- Pulse Amplifiers
- Solid-State Relays

ABSOLUTE MAXIMUM RATINGS ($T_A = +25^\circ\text{C}$ unless otherwise specified)

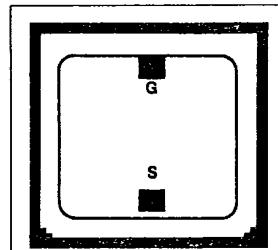
Drain-Source Voltage		Peak Pulsed Drain Current	... + 2.0A
SD1137, TN0106	+ 60V	Continuous Device Dissipation	
TN0110	+ 100V	$T_A = +25^\circ\text{C}$	$T_C = +25^\circ\text{C}$
SD1137, TN0106	+ 60V	0.30W	1.0W
TN0110	+ 100V		
Gate-Source Voltage	$\pm 30\text{V}$	Linear Derating Factor	
Continuous Drain Current		$T_A = +25^\circ\text{C}$	$T_C = +25^\circ\text{C}$
SD1137BD	$T_A = +25^\circ\text{C}$	3.0mW/ $^\circ\text{C}$	10mW/ $^\circ\text{C}$
TN0106N3 }	.25A		
TN0110N3 }	.23A		
		Operating Junction and Storage Temperature Range	-55 $^\circ\text{C}$ to + 150 $^\circ\text{C}$
		Lead Temperature (1/16" from mounting surface for 30 sec)	+ 250 $^\circ\text{C}$

PIN CONFIGURATION



**PACKAGE DIMENSIONS
(TO-92) TO-226AA**
(See Package 5)

CHIP CONFIGURATION



Dimensions: .054 x .051 x .020 in.
Drain is backside contact.

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ELECTRICAL CHARACTERISTICS ($T_A = +25^\circ\text{C}$ unless otherwise specified)

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#	PARAMETER	SD1137			TN0106			TN0110			UNIT	CONDITIONS	
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX			
1	BV _{DSS} Drain-Source Breakdown Voltage	60	90		60	90		100	115		V	I _D = 1.0mA, V _{GS} = 0	
2				100									
3						500							
4										500			
5	I _{DSS} Drain-Source Off Leakage Current	.01	1.0								μA	V _{DS} = 48V	T _A = +125°C
6					.01	10						V _{DS} = 48V	V _{GS} = 0
7												V _{DS} = 80V	
8												V _{DS} = 60V	
9	I _{GSS} Gate-Body Leakage Current		±1.0			±1.0			±1.0		μA	V _{GB} = ±30V	V _{DS} = 0
10	V _{GS(th)} Gate-Source Threshold Voltage	0.5		1.5	0.5		1.5	0.5		1.5	V	V _{DS} = V _{GS} , I _D = 1.0mA	
11	r _{D(on)} Drain-Source On Resistance			4.5			4.5			4.5	ohms	V _{GS} = 5V, I _D = .25A	
12				2.5								V _{GS} = 10V	I _D = 1.0A
13							3.0			3.0			I _D = 0.5A
14	I _{D(on)} On Drain Current			.75			.75				A	V _{GS} = 5V	V _{DS} = 25V
15				2.0			2.0					V _{GS} = 10V	
16	g _{fs} Common-Source Forward Transcond.	300	500		225	500		225	500		mmhos	V _{DS} = 25V	I _D = 0.5A
17					1.5							V _{DS} = 20V	f = 1KHz
18	V _{SD} Source-Drain Forward Voltage						1.5			1.5	V	I _{SD} = 0.8A	V _{GS} = 0
19												I _{SD} = 0.5A	
20	C _{iss} Common-Source Input Capacitance			60			60			60	pF	V _{DS} = 25V	
21	C _{oss} Common-Source Output Capacitance		11	35		11	35		11	35		V _{GS} = 0	
22	C _{rss} Common-Source Reverse Transfer Capacitance		1.5	8.0		1.5	8.0		1.5	8.0		f = 1MHz	
23	t _{on} Turn ON Time		8.0	10		8.0	10		8.0	10	nS	V _{DD} = 25V, V _{G(on)} = 10V	
24	t _{off} Turn OFF Time		8.0	12		8.0	12		8.0	12		R _G = 51Ω, R _L = 25Ω	

NOTE 1: Pulse Test, 80μSec, 1% Duty Cycle